Preface of the 2013 IAENG International Conference on Electrical Engineering Special Session: Design, Analysis and Tools for Integrated Circuits and Systems

The International Workshop DATICS-IMECS'13: Design, Analysis and Tools for Integrated Circuits and Systems in the International MultiConference of Engineers and Computer Scientists 2013 will take place in Hong Kong, 13-15 March, 2013.

DATICS Workshops were initially created by a network of researchers and engineers both from academia and industry in the areas of Design, Analysis and Tools for Integrated Circuits and Systems. Recently, DATICS has been extended to the fields of Communication, Computer Science, Software Engineering and Information Technology.

The main target of DATICS-IMECS'13 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all aspects of DATICS.

The International Program Committee (IPC) of DATICS-IMECS'13 consists of about 150 experts in the related fields of DATICS-IMECS'13 both from academia and industry. DATICS-IMECS'13 is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), Minteos (Italy), KATRI (Japan & Hong Kong), Distributed Thought (UK), ASIC LAB - Myongji University (South Korea), Baltic Institute of Advanced Technology - BPTI (Lithuania), Solari (Hong Kong), Transcend Epoch (Hong Kong) and Xi'an Jiaotong-Liverpool University - XJTLU (China - UK).

The DATICS-IMECS'13 Technical Program includes 10 papers which are organized into lecture sessions. On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-IMECS'13. We hope that you will enjoy the workshop and find the DATICS-IMECS'13 Technical Program exciting.

Ka Lok Man and Nan Zhang, DATICS-IMECS'13 IPC Chairs.

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